

Please amend the following claims as presented, below, in clean-unmarked format:

1. (Amended) A package, comprising:

a substrate with an inner surface to which a die is to be attached, forming electrical connections through the substrate, between the die and the exterior of the package;

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a lid with an inner surface facing the inner surface of the substrate;
thermal attach disposed between the die and the inner surface of the lid;
and

sealant disposed between the substrate and the lid in a pattern with at least one break in the pattern remaining subsequent to the substrate and lid being assembled together.

23. (Amended) An apparatus, comprising:

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a substrate with an inner surface;
a lid with an inner surface facing the inner surface of the substrate;
a die on which electronic circuitry is disposed, enclosed between the substrate and the lid, and attached to the inner surface of the substrate which provides electrical connections between the die and the exterior of the package;
thermal attach disposed between the die and inner surface of the lid; and
sealant disposed between the substrate and the lid in a pattern with at least one break in the pattern remaining subsequent to the substrate and lid being assembled together.

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27. (Amended) The apparatus of claim 23, wherein the die is attached to the substrate using a controlled collapsed chip connection.